



DTE Power via MDI *Power Feeding Alternatives*

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Assumptions:

- Load should be connected between two pairs
- Range of applications will dependant on amount of power available



Power Feeding Alternatives

- **Out-of-Band (7&8, 4&5)**
- **In-Band (3&6, 1&2)**
 - **Phantom feeding**
 - **Parallel feeding**
 - **Common Mode feeding with Capacitors**
- **All Pairs**



Available Power

Over a Single Class D Channel Wire Pair

Physical limitations

- Cables - Class D Category 5 - Limited to 80Vdc
(some manufacturers do not rate max DC voltage)
- Connectors - RJ45 Rated for 250V/1.5A
- Connecting Hardware - PCB traces will support **250mA**

Safety & Marketing Considerations

- Safety Standards rate voltages below **60Vdc** as SELV
- We estimate a strong preference to 24Vdc or 48Vdc
- 24/48V can be supported by battery backup

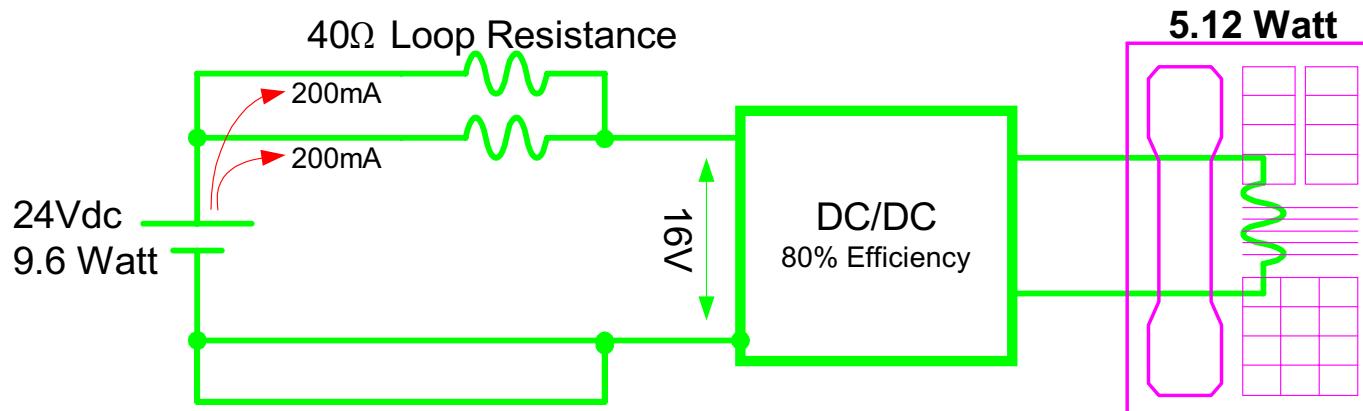
Infrastructure

- Channel Maximum Resistance **40 Ohm** (typically less than 20 Ohm)
Including horizontal cable, patch cabling, connectors & connecting hardware

Available Power Over Cat 5 Cabling Plant

Assume:

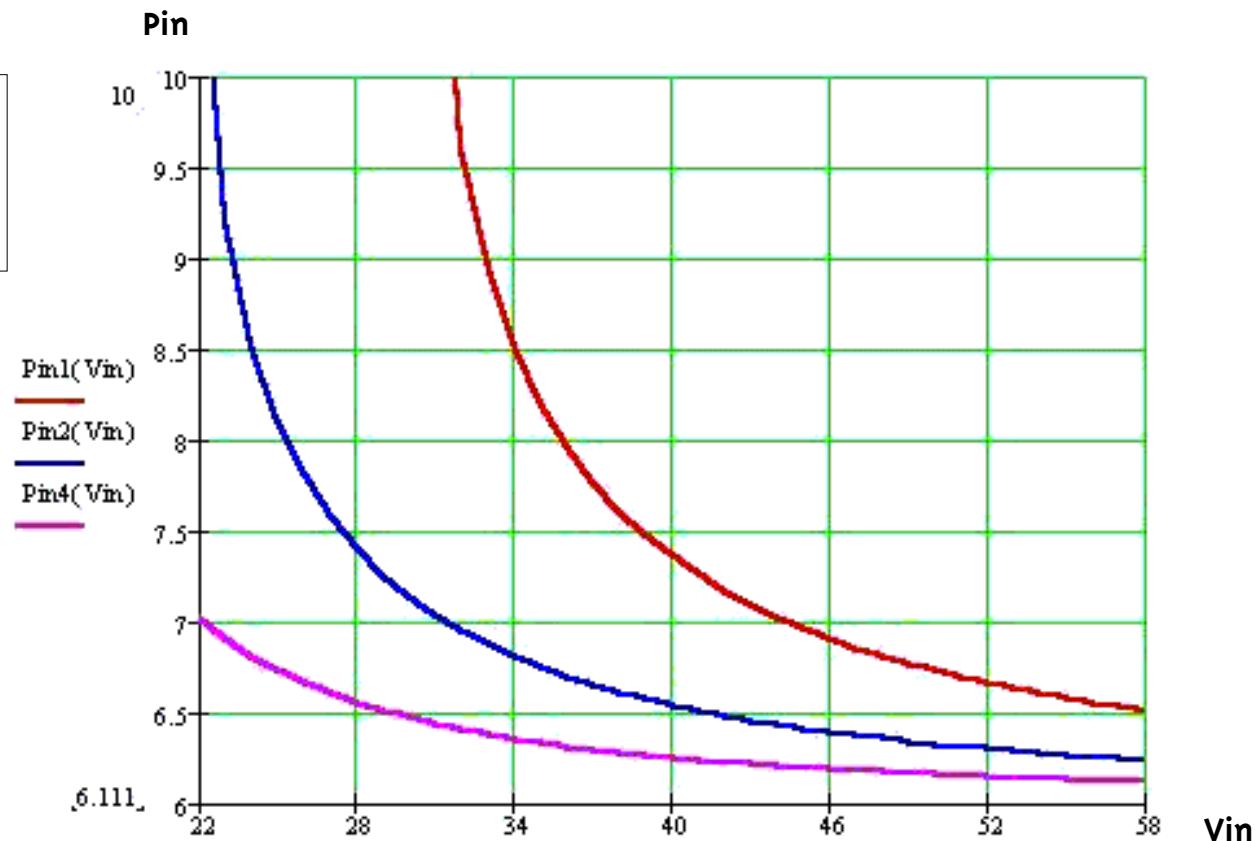
- 24Vdc/400mA Input (200mA on each pair)
- 80% DC/DC Efficiency
- 40 Ohm Maximum Channel Resistance
- Dual Twisted Pair Feeding



- Maximum available power to DTE using two pairs = 5.12 Watt
- Maximum available power to DTE using four pairs = 10.24 Watt

Required Source Power to Feed a 6 Watt DTE

Using:
 •Single wire pair
 •Dual wire pair
 •Quad wire pair



Required Source to Power a 6W DTE

Pload := 6

line_impidance := 40 100m UTP Single Pair max. impedance

$$Pin1(Vin) := \frac{Vin}{\left(\frac{2 \cdot line_impidance}{2} \right)} \cdot \left[Vin - \left(Vin^2 - 4 \cdot line_impidance \cdot Pload \right)^{\frac{1}{2}} \right]^{\frac{1}{2}}$$

$$Pin2(Vin) := \frac{Vin}{\left(\frac{2 \cdot line_impidance}{2} \right)} \cdot \left[Vin - \left(Vin^2 - 4 \cdot \frac{line_impidance}{2} \cdot Pload \right)^{\frac{1}{2}} \right]^{\frac{1}{2}}$$

$$Pin4(Vin) := \frac{Vin}{\left(\frac{2 \cdot line_impidance}{4} \right)} \cdot \left[Vin - \left(Vin^2 - 4 \cdot \frac{line_impidance}{4} \cdot Pload \right)^{\frac{1}{2}} \right]^{\frac{1}{2}}$$



In-Band Technical Challenges

- **Degradation of link performance:**
 - Near end & alien crosstalk via DC supply bus
 - Channel attenuation, S/N
 - Link balance
 - Susceptibility to radiated & conducted common & differential mode noise
 - Link impedance matching
 - Currents via transformers due to unbalance pairs
- **Protection of ordinary (non MDI powered) DTE**



Out-of-Band Feeding Technical Challenges

- **Detection & Protection of “Bob Smith” terminations
(relatively simple)**
- **Maintaining FCC Class B compliance by maintaining
termination on mid point insertion**

Comments

- **Complexity, Cost & Time-to-Market of In-Band Feeding Will be Higher**
- **Justified only where:**
 - **2 Pairs Installations**
 - **Future 1000base-T to DTE**
 - **4 pair could be used for high power applications**



Question

- Should the standard be scalable to allow two
and four pair feeding?